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Serial Number: 10705579

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PALM INTRANET**Inventor Information for 10/705579**

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US 20040231996 A1	20041125	Electroplating using DC current interruption and variable rotation rate	205/137	205/143	Webb, Eric G. et al.
US 20040136681 A1	20040715	Erbium-doped oxide glass	385/142	385/129	Drewery, John S. et al.
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US 4322739 A	19820330	Processing of N.T.S.C. color television signals	348/392.1		Drewery; John O. et al.
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US 4288810 A	19810908	Method of and apparatus for deriving a PAL color television signal corresponding to any desired field in an 8-field PAL sequence from one stored field or picture of a PAL signal	348/662	348/453; 348/654	Drewery; John O. et al.
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